



Material Content Data Sheet



Sales Product Name				IPD031N03L G		Issued		19. August 2018	
MA#				MA001662058					
Package				PG-TO252-3-311		Weight*		317.81 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.247	0.71	0.71	7070	7070	
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		135		
	non noble metal	iron	7439-89-6	0.143	0.05		451		
	non noble metal	copper	7440-50-8	143.098	45.01	45.07	450259	450845	
	non noble metal	aluminium	7429-90-5	3.562	1.12	1.12	11208	11208	
wire	non noble metal	aluminium	7429-90-5	3.562	1.12	1.12	11208	11208	
encapsulation	organic material	carbon black	1333-86-4	0.316	0.10		994		
	plastics	epoxy resin	-	19.062	6.00		59978		
	inorganic material	silicondioxide	60676-86-0	124.160	39.07	45.17	390672	451644	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11768	11768	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	272	273	
solder	non noble metal	tin	7440-31-5	0.043	0.01		135		
	noble metal	silver	7440-22-4	0.054	0.02		169		
	non noble metal	lead	7439-92-1	2.056	0.65	0.68	6468	6772	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		60		
	non noble metal	copper	7440-50-8	19.177	6.03	6.04	60342	60420	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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